Santa Clara Valley Section Corporate Liaison Program (CLP)

Oct. 8, 2016
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Outstanding Large Section Award
Santa Clara Valley Section
2016

Outline

- **What we are doing and why**
- **What we did**

How we did it

- **What we will do**
- **What you can do**

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Santa Clara Valley Section Overview

❯ ~13,000+ members

❯ 32 Chapters

❯ 4 Affinity Groups (Consultants Network, Life Members, WIE, Young Professionals)

❯ 4 Committees (K-12, SIGHT, Tech History, TOPS)

❯ 10 Student Units in 4 Universities (San Jose State U., Santa Clara U., Stanford U., UC Santa Cruz)

Region 6 Central Area Meeting Oct 8, 2016

Chapters

Antennas & Propagation	Circuits & Systems
Communications	Components Packaging & Manufacturing Technology
Computational Intelligence	Computer
Consultants' Network	Consumer Electronics
Control Systems	Education
Electromagnetic Compatibility	Electron Devices
Engineering In Medicine & Biology	Information Theory Group
Instrumentation & Measurement	Magnetics
MEMS & Sensors Chapter	Microwave Theory & Techniques
Nanotechnology	Photonics
PhotoVoltaics	Power Electronics
Power & Energy & Industry Applications	Product Safety Engineering
Reliability	Robotics & Automation
Signal Processing	Solid State Circuits
Life Members	Technology Management
Vehicular Technology	*Women in Engineering*

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What we are doing and why

- CLP is a result of SCV Section's Corporate Relationship Initiative
- Goal is to have a formalized way to build relationships with our corporate citizens
  - vs. ad-hoc or nothing at all
  - The intent is a **<u>Long Term</u>** effort!
  - To establish win-win partnership
- One mission is to solve difficulty of find free meeting venues from local companies
- We recognized this as a wider issue and an ongoing need. e.g. $50k donation from Marvell to Region 6

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What we did

- Organized a team with SCV volunteers
- 23 Liaisons (& contacts) found!
- 14 companies attended our first ever Liaison lunch event in November!
    - We presented the Liaison Program
    - We presented our Section & Chapters
    - Opportunity: GHTC & SIGHT
    - Opportunity: Student Conference (~April)
    - Opportunity: TMC involvement
    - Q&A
- Liaisons wanted quarterly events!
- Event info: http://bit.ly/IEEE-CLP-11-21-13 (Case Sensitive)

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How to find the CLP Liaison

❯ Liaison Criteria:

  – senior level individual within the corporation

  – Committed to attend quarterly meeting & communicate with his/her company

  – Has a good understanding of IEEE's programs and its company's Corporate's Social Responsibilities (CSR) and Engineering initatives

❯ How to find CLP

  – Personal network

  – Reach out to the CTO office

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What we did (cont.)

Companies with Liaisons (or contacts):

Attended 11/21/13	
1	Altera
2	AMD
3	Cisco
4	Corning
5	Google
6	HP
7	Maxim Integrated
8	NVIDIA
9	Oracle
10	Renesas
11	Samsung
12	Silicon Image
13	Underwriter Labs
14	Xilinx

Could not attend	
1	Cadence
2	EMC
3	Imagination Tech
4	Intel
5	NASA Ames
6	SanDisk
7	Seagate
8	Synopsys
9	Texas Instruments

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What we did (cont.)

Time	Min		Who	Slides
12:00	**15**	**Arrive, get food**		
12:15	**15**	**Seated, eating**		
12:30	**10**	**Welcome, CLP Mission, introductions**	**Ed Aoki**	**5**
	9	**IEEE, Section, More about CLP, Liaisons;** **• Feedback**	**John Swan**	**9**
	10	**eGRID, Chapters, hot Chapter events - regular tech meetings and special seminars, etc.;** **• Feedback**	**Paul Wesling**	**11**
	7	**Opportunity 1: Student Congress** **• quick feedback**	**Mostafa Mortezaie**	**2**
	7	**Opportunity 2: GHTC & SIGHT** **• quick feedback**	**Joseph Wei, for Daniel Lottis**	**3**
	7	**Opportunity 3: Technical Management Council** **• quick feedback**	**John Delaney**	**3**
13:20	**5**	**• 3-opportunity feedback**	**John Swan**	
13:25	**5**	**General discussion**	**John Swan**	
13:30		**Depart**		

Also attended for IEEE: Sachin Desai, Ram Sivaraman

Presentations and handout posted at **http://bit.ly/IEEE-CLP-11-21-13**
(Case Sensitive)

Region 6 Central Area Meeting Oct 8, 2016

How we did it

- Started planning Jan. 2013
- Presented concept and approach to SCV Section ExCom
- Started company and contact list
- May: An "Action Committee" was formed
- Utilized **Google Drive** for common committee access to the 'Golden' liaison status spreadsheet list

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How we did it (cont.)

- Worked to use the company contacts to identify liaisons
- Late July: Started brief but weekly conf calls
- Early October: Ended weekly conf calls
- Continued to contact companies and build Liaison (& contact list) throughout.

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How we did it (cont.)

- Event was selected for late November
  - To give us the year to find liaisons
- Committee iterated on possible agenda options
- Goal of meeting was met:
  - A variety of brief informational presentations
  - Ample time for liaison feedback & discussion
  - Respected attendees time

How we did it (cont.)

- Planned and prepared well for the liaison event on Nov. 21.
  - 90 min total minus 30 min. for lunch
  - Michael's on Shoreline, Mt. View
- Prepared badges
- IEEE Committee sat among attendees
- All event info was posted:
  - **http://bit.ly/IEEE-CLP-11-21-13** (Case Sensitive)

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Topics presented

	11/21			8/20	
Local IEEE events	🟦	🟦	🟦	🟦	
Student Conference	🟦	🟦	🟦	⬜	
GHTC & SIGHT	🟦	🟦	🟩	⬜	Intel
TMC	🟦	⬜	⬜	⬜	
WIE	⬜	🟦	🟩	🟦	Altera
SPS	⬜	🟦	⬜	🟩	AMD
Young Professionals	⬜	⬜	🟩	⬜	Maxim
Techmanity	⬜	⬜	⬜	🟩	Samsung SSI
Training - CS	⬜	⬜	⬜	🟦	
Liaison Discussion	⬜	🟩	🟩	🟩	

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Other 🟩

All materials posted at:

http://bit.ly/
IEEE-SCV-Liaison-Event-Materials

14
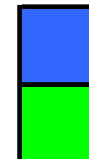
Typical Agenda (from 8/20/14)

12:00 PM	Arrive, get food		
12:30 PM	Welcome	Tom Coughlin	IEEE, Region 6 Dir. Elect
	Agenda overview, new introductions	John Swan	IEEE
	Hot Chapter, Section & Region events	Joseph Wei & Tom Coughlin	IEEE
	SPS Chapter Restart Signal Processing Society	Radha Giduthuri	AMD
	WIE Update Women In Engineering	Suzette Pangrle	IEEE
	GHTC / SIGHT Update – Global Humanitarian Tech. Conf.	Catherine Nelson	Intel
	New Opportunity: Techmanity	Daniel (Seung) Yoo	Samsung - SSI
1:07 PM	Training: Bringing global resources to you locally – discussion • Some things we already have • What are your needs	Matt Peters	IEEE Computer Society
1:22 PM	Liaison Role Discussion	Tom Coughlin John Swan	All
1:30 PM	Dismissed		

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What we will do

- We will continue with quarterly lunch events
- We will expand the Liaison list to include:
  - Texas Instruments
  - Microsoft
  - Marvell
  - Micron
  - Agilent
  - TSMC
  - Citrix
  - Juniper Networks
  - Qualcomm
  - Broadcom
  - HGST (West. Dig.)
  - ARM
  - Brocade

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Add Universities

- Universities are included in Corporate Relations Initiative!
  - They were on our CLP list from the start
- Decided to hold off until the program is established with companies
  - Focus our efforts for success
  - Learn by doing
  - Interests expected to be different
- *Update*: SCV website porting to Wordpress by SJSU students

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Most Recent List of CLP companies

- Altera
- AMD
- Apple
- ARM
- Cadence
- Cisco
- Corning
- EMC

- Google
- HP
- HGST
- Imgtek
- Intel
- Juniper
- Keysight
- LG

- Maxim
- Microsoft
- NASA
- NetApp
- NVIDIA
- Oracle
- Renesas
- Samsung

- SanDisk
- Seagate
- Silicon Image
- SK
- Synopsys
- TI
- UL
- Xilinx

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Recent Results

❯ Additional corporate venues were offered to IEEE SCV Chapters

❯ Corporate sponsors were connected with WIE ILC and GHTC

❯ Secured AMD CEO & other corporate executives as speakers at WIE ILC 2015 & 2016

❯ Connected WIE related programs amongst several corporations

❯ E-Grid has been included in HP's internal employee's communication

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What you can do

- Identify some known collaboration opportunities with local tech companies (e.g. conference/ workshop, recruiting, humanitarian projects, etc.)

- Request for Section funding support (if needed) for holding quarterly meetings with Liaisons

- Identify someone at a significant management level at your chapter meeting host company to be your Corporate Liaison?

- Start the first meeting once you have a list of 6 ~ 10 corporate liaison

- Contacts for SCV Section CLP, Ram Sivaraman (ramsivaraman@ieee.org), and, Joseph Wei (joseph.wei@ieee.org)

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